

# ADVANCED DIRECT IMAGING by ALTIX





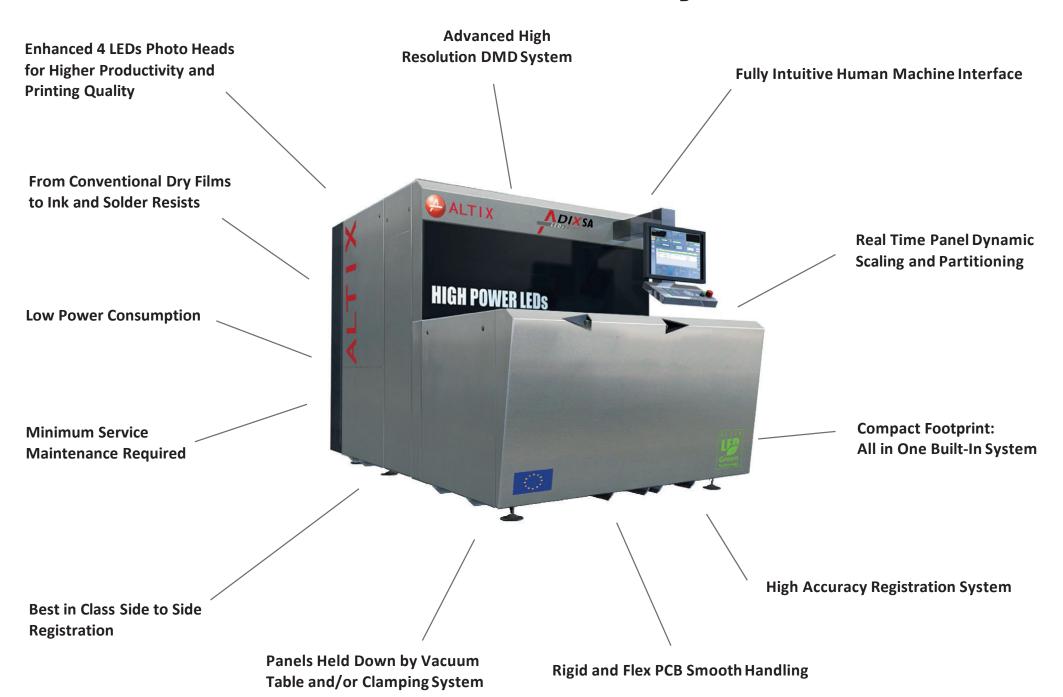




## **DIRECT IMAGING WITH US**

**Direct Imaging Solution for PCB, FPCB, PCM (...)** 

## **ADVANCED DIRECT IMAGING by ALTIX**



## **ADIX Specifications**

	Panel size	From 228 x 254mm up to 610 x 762mm   From 9"x10" up to 24"x30"		
Panel	Panel thickness	0.04 to 6mm   1.6 to 236mils		
	Warp and twist	0.04 to 0.8mm   1.6 to 31mils ¤ panel thickness: 1% of the diagonal 0.8 to 6mm   31 to 236mils ¤ panel thickness: 0.5% of the diagonal		
	Weight	6kg max (13.22lbs)		
Web	Image size Web Thickness	From 190mm x 190mm (7.5"x7.5") up to 610mm x 685mm (24"x27") 0.030 to 0.5mm		
		Adix SA		Adix SA neo
Imaging	Resolution - L/S Resolution - DAM Edge Roughness Depth of Focus Autofocus Image to panel registration Side to side registration	10/10μm   0.4/0.4mil <sup>(1)</sup> NA ± 0.5μm 100μm ± 8mm   ± 315mils ± 8μm   ± 0.31mil ± 12μm   ± 0.47mil	20/20μm   0.8/0.8mil <sup>(1)</sup> 25μm   1mil ± 1.5μm 200μm	30/30μm   1.2/1.2mils <sup>(1)</sup> 50μm   2mils ± 3μm 400μm
Throughput	Exposure time	14s with 30mJ/cm <sup>2</sup> resist for 457 x 610mm (18"x 24") image size (6 heads) (2)		
Process	Imaging resist materials Resist sensitivity Exposure spectrum Applications Production types	Conventional dry films or specific for DI x Ink & solder resists From 10 to 1,250mJ/cm² and above 4 wavelengths per Photo Head: 365/380/395/405nm PCB x FPCB / Flex x Photo Chemical Milling x IC Substrate x Touch Panel Inner Layers x Outer Layers x Soldermask (PSR)		
Graphic User Interface	Altix Direct Imaging Suite <sup>TM</sup> Data Input	22 » touch screen, intuitive software, SPC capabilities, multilanguage Extended Gerber, ODB++, (others upon request)		
	Data Input	Extended Gerber, ODB++, (others upon request)		
General utilities & Foot print Water supply Machine weight Dimensions  Air supply 6 bars   1.5m³/min Water pressure 3~5 bars × Flow rate: 23l/min @ 12°C or 33l/min @ 3,500kg (7,716lbs) L: 2,870mm (113") W: 1,750mm (69") H: 1,870mm (74")				

## **ADIX Semi-Automatic & Fully-Automatic Direct Imaging Product Range**



#### **Adix SA Semi-Automatic** Panel to Panel DI Exposure

Semi-Automatic Direct Imaging solution for QTA, highmix low and medium volume production dedicated for all processes: Inner Layers, Outer Layers and Soldermask (PSR)



#### **Adix SA neo Semi-Automatic** Panel to Panel DI Exposure

**Adix RtR** 

Adix SA neo is the Fastest Imaging System with **Customized Number of Photo Heads & Stripes. From** 1 to 7 Photo Heads and upgradable on site. It is dedicated for all processes.



#### Adix CS / F **Compact Standardized / Flip Compact - Island of Automation Fully Automatic Double Side**

The system is designed to automatically load and unload panels into an Adix Direct Imaging system from either angular or slot cassettes.

An automatic flip & cleaning functions are integrated. The system is able to handle multiple batches and different panel sizes.

This compact automation is dedicated for all resists: dry film & solder resists and upgradable on site.



#### Adix PT / F Pass-Through / Flip **In-Line Automation Fully Automatic Double Side**

Integrated automation for fully-automatic Direct Imaging process in-line or island of automation,

Pass-through double-sided production with « in the air » flip.

This compact automation is dedicated fol all resists: dry film & solder resists and upgradable on site.



### **Roll to Roll DI Exposure Fully-Automatic** Adix Roll to Roll is a fully automatic Direct Imaging

designed as a single sided Roll to Roll exposure system for fine line resolution, tight registration and high throughput capabilities.

It can handle all types of web for Flex Printed Circuit Boards, Photo Chemical Milling, Touch Panel, Thin Film Photovoltaic. etc...

#### ALDS-Power4+™

Advanced high power Leds with high resolution DMD System. The heart of the system is a creative combination of 4 high-density LEDs light sources through a unique optical device coupled to a high frequency (up to 20kHz) DMD coordinated with a graphic signal and projectionlens.

This combination enables our ADIX solution to perform high-resolution line and space down to  $10\mu m$ .

#### ALDS-Power4+™

Highly accurate real time scaling and distortion compensation technology responds to the PCB material variations. Each digital image can be scaled to match with the panel distortion.

For each panel, different scale factors can be applied with dynamic imaging modes: linear (Trapezoidal scaling, Orthogonal scaling) and non-linear (Polygonal scaling).

#### **High Accuracy Registration**

A multiple CCD cameras vision system enables featuring image to panel registration down to  $\pm 8\mu m$  for high-end HDI designs.

Our solution can align the panel via a through hole or various alignment marks.

Our side-to-side registration for inner layers enables high accuracy alignment down to  $\pm 12 \mu m$  thanks to our exceptional registration system with adjustable points fitting the panel size.

#### Smart Vacuum & Clamping Technology™

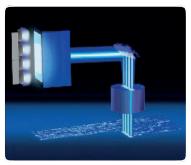
A unique Vacuum & Clamping mechanism offers an automatic selectable vacuum system.

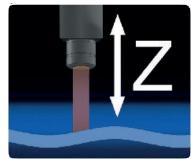
Vacuum and clamping are automatically monitored according to the panel size.

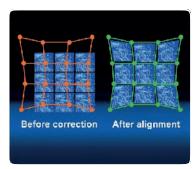
This clamping system can safely hold warped PCBs and handle panel thickness from  $40\mu m$  to 6mm.

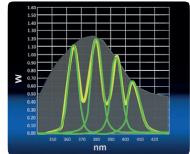
In addition, with the autofocus function, it allows a perfect imaging compared to other systems having only a vacuum table without clamping mechanism.

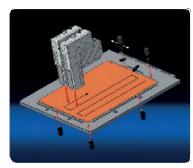
## **ADIX Advanced Features**

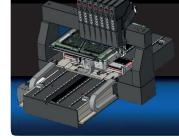


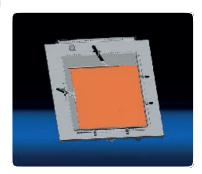














#### **High Dynamic Autofocus Function**

Highly precise and dynamic autofocus system is integrated inside each imaging head. The heads get real time feedbacks in order to take into account the warping and surface thickness variations of the board at  $\pm 8$ mm.

This state of the art tool plus the depth of focus of the head, which allows imaging in a consistently suitable state, drastically reduce the occurrence rate of imaging errors.

#### **Multi-Wavelenghts UV-LED**

The combination of different UV light wavelengths enables to polymerize a large range of dry film, ink and solder resists.

With 4 LED wavelengths (365/380/395/405nm) and by adjusting the output ratio, it is possible to obtain the most efficient and fast printing for each type of dry resists or soldermask. UV-LED consumes less energy, generates less heat, and lasts much longer than typical laser diode or blue laser based on light sources.

## Number of Light Engines depending on your capacity. Upgradable on site

Our modular and flexible imaging technology ALDS-Power4™ can be adapted to your throughput requirements. Also, the number of Photo Heads can be chosen accordingly when defining your new Direct Imaging equipment. This number of Photo Heads can be enlarged from 1 to 7 anytime in the future to match with your expanding needs.

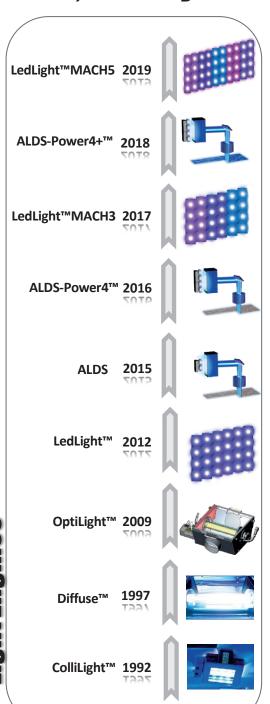
This incremental investment enables to have a fully optimized system, which means a quicker Return Of Investment.

#### **Human Machine Interface (HMI)**

Fully intuitive interface enables a friendly-user utilization for the operators. A state of the art touch screen graphical user interface enables an easy operating such as: quick job setups, parameters monitoring, full diagnosis, or process optimization.

Our powerful software "ALTIX Direct Imaging Suite™" offers more with multilingual capabilities and our statistical module "Altix Statistical Process Control Module".

## **ALTIX**, over **30** years of innovations and performances!









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Europe: Altix France – HQ Email: central@altix.fr

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## *Imaging with us!*





www.altix.fr